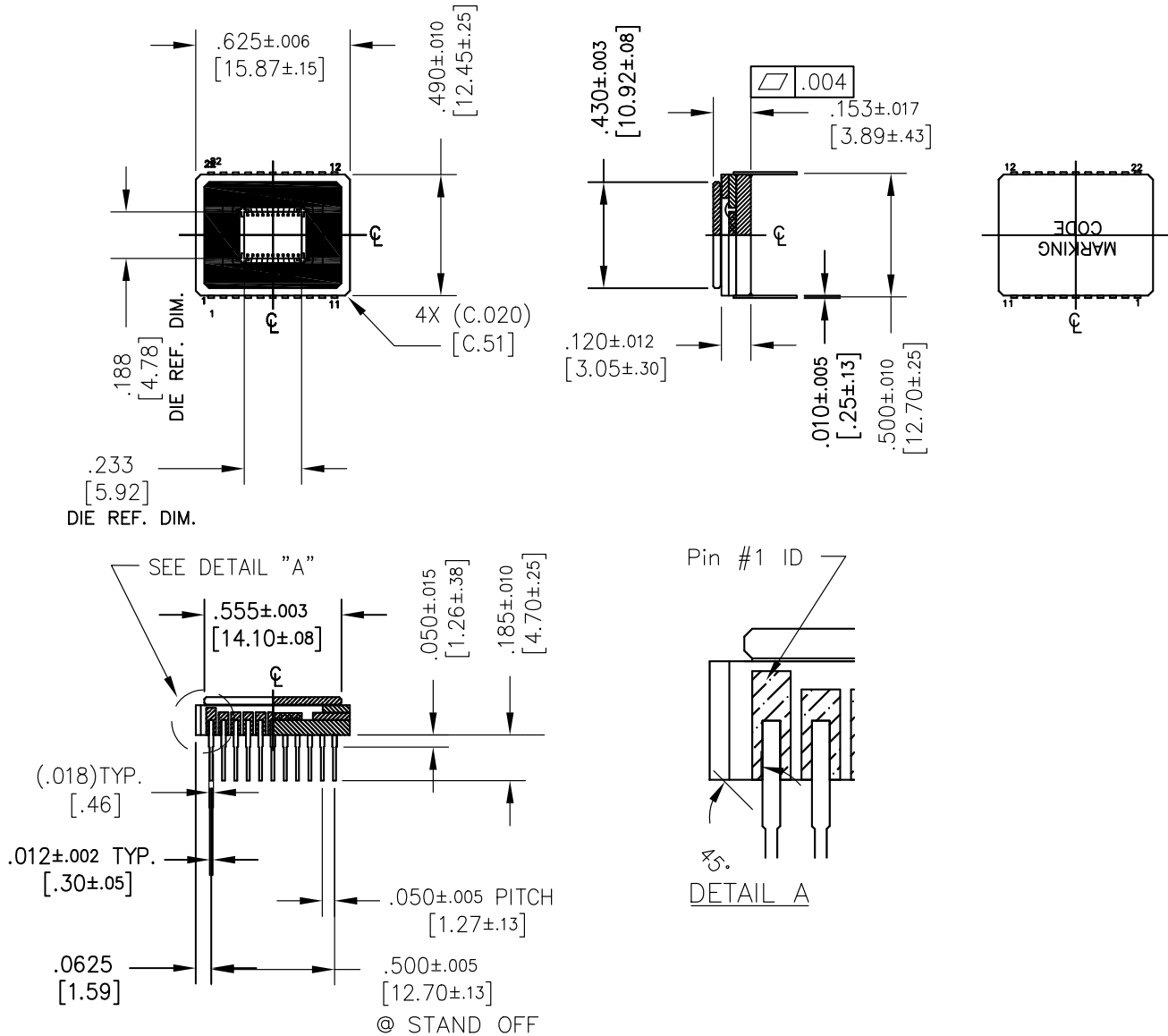


**MECHANICAL CASE OUTLINE**  
**PACKAGE DIMENSIONS**

**CERAMIC DIP 22**  
**CASE 125AS**  
**ISSUE O**

DATE 30 JUN 2014

SHOWN WITH SEALED COVER GLASS



NOTES:

- LID SHALL NOT EXTEND BEYOND CERAMIC EDGE
- LIGHT SHIELD SHOWN FOR REFERENCE ONLY. QUARTZ VERSION IS SMALLER

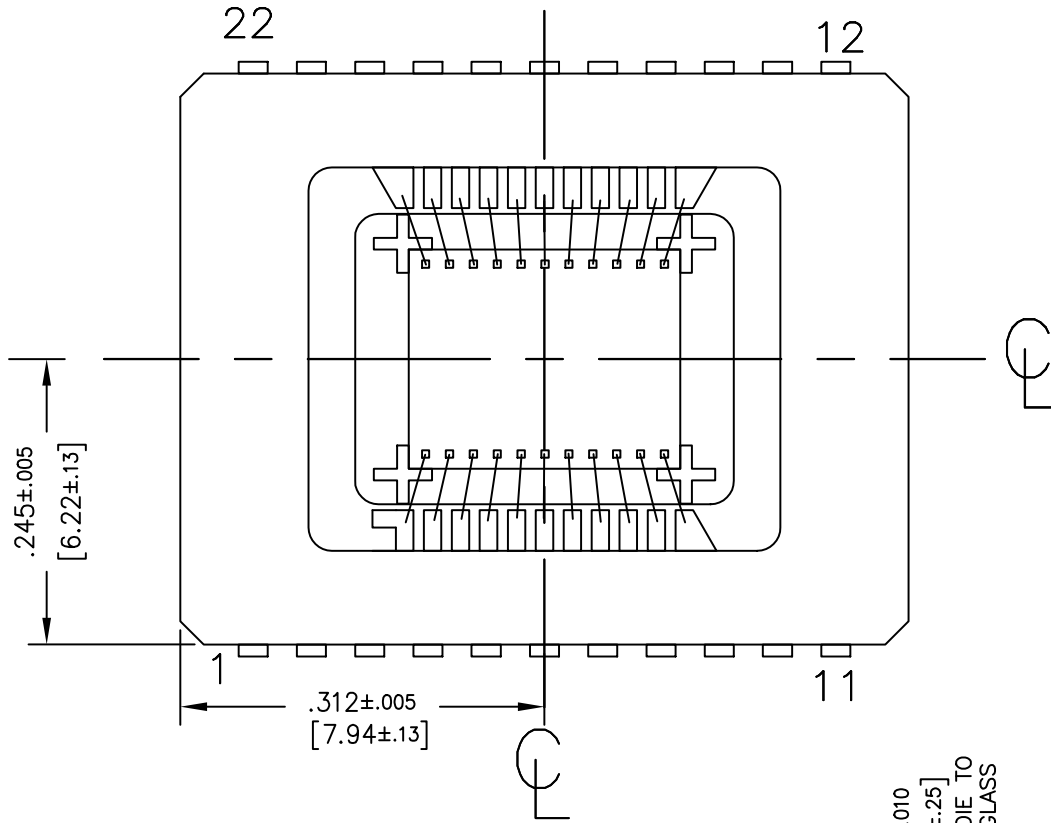
Dimensions in: Inches [mm]

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DESCRIPTION:	CERAMIC DIP 22	PAGE 1 OF 3

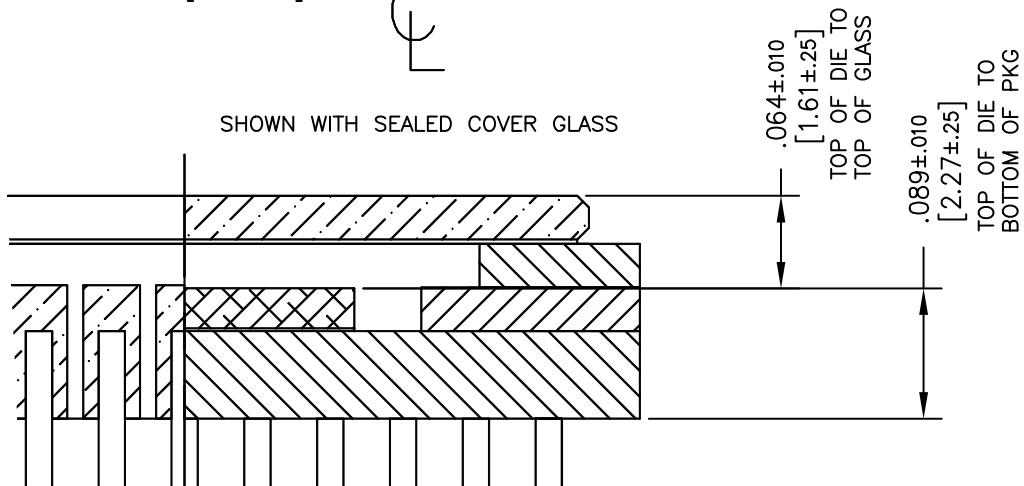
**CERAMIC DIP 22**  
**CASE 125AS**  
**ISSUE O**

DATE 30 JUN 2014

SHOWN WITHOUT COVER GLASS



SHOWN WITH SEALED COVER GLASS



**NOTES:**

1. CENTER OF IMAGE AREA IS OFFSET FROM CENTER OF PACKAGE BY (0.00, 0.00) IN NOMINAL.
2. DIE IS ALIGNED WITHIN +/- 1 DEGREE OF ANY PACKAGE CAVITY EDGE.

**Dimensions in: Inches [mm]**

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